



FBP3100 Polishing Pad

New Technology for Metal Polishing

DESCRIPTION

The FBP3100 polishing pad utilizes new polymer technology to deliver an open cell, porous pad designed for use in CMP metal polishing applications. The FBP3100 polishing pad was designed to provide reliability and consistency in cutting-edge semiconductor manufacturing processes.

Characteristics	
Vertical Orientation	19 – 22 mils
Deflection	0.8 – 2.0 mils
Compressibility	3 – 6.8%
Total Thickness	26.5 – 29.5 mils
Pore Count	30 – 230/mm ²
Weight Density	0.52 – 0.66 g/cc
Groove Depth	7 – 11 mils

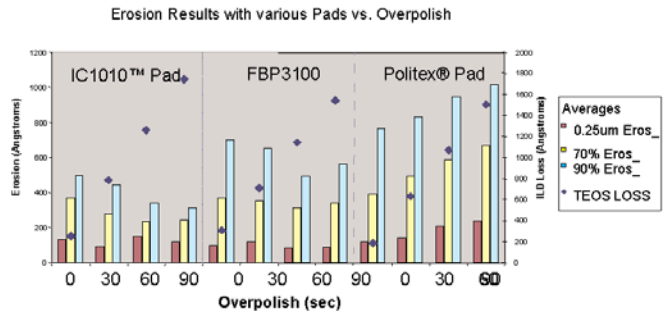
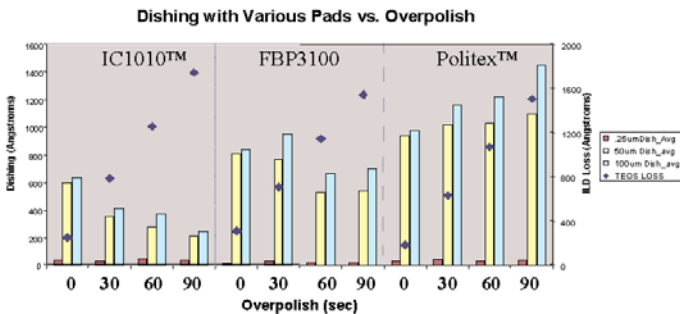
KEY FEATURES

- Exceptional thickness control
- Superior consistency in physical properties
- Endpoint detection capable
- Pad size and groove patterns can be customized
- Results recorded from Sematech 854 mask, copper wafers
- The FBP3100 polishing pad is the ideal choice for CMP applications that require excellent defectivity results while achieving good dishing and erosion performance

BENEFITS

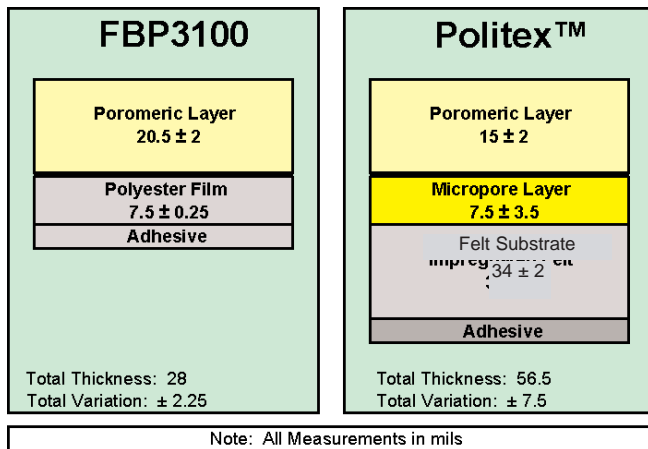
- Good dishing and erosion performance
- Excellent defectivity performance
- Allows a reduction in slurry flow for some tungsten polishing applications

Cu CMP Barrier Removal Results with CUS1351 Barrier Slurry



creating the
flawless surface

PAD STRUCTURE



PRODUCT MANUFACTURING

FBP3100 polishing pads are produced at state-of-the-art manufacturing facilities in Newark, Delaware, Nara, Japan, and Mie, Japan. These facilities have the demonstrated capacity to handle the high-volume production requirements for all semiconductor wafer facilities with the flexibility to deliver customized pads addressing the needs of unique CMP processes. Failure Mode Effect Analysis (FMEA) control plans are incorporated into each processing step. We have implemented quality and manufacturing systems to provide products that are manufactured with a Six Sigma mentality. Each pad is rigorously inspected to ensure that customers receive the highest quality products. Our ISO9001:2000 certification and MRPII Class A status ensure that high-quality products are delivered to customers on time.

PACKAGING

FBP3100 pads are delivered on a pressure sensitive adhesive (PSA) backed with a non-particulate release liner. Each pad is individually bagged and heat sealed to ensure that the cleanliness of each

pad is maintained during transportation.

STORAGE

These pads should always remain flat. Bending the pads can cause wrinkles in the PSA and premature delamination of the release liner. It is recommended that Rohm and Haas Electronic Materials pads be stored and transported in their original boxes. It is recommended that pads be maintained at temperatures between 10°C to 24°C (50°F to 75°F) and <50% humidity. FBP3100 pads can be exposed for up to six months to temperatures of -17°C to 48°C (0°F to 120 °F) and 100% humidity without any impact to product performance. In the event of product exposure outside the recommended conditions, contact Rohm and Haas Electronic Materials technical personnel for recommendations. In all cases, allow the pad to return to normal room temperatures, 10°C to 24°C (50°F to 75°F), prior to use.

SHELF LIFE

Standard shelf life for FBP3100 pads is one (1) year from the date of manufacture. It is recommended that pads be stored in their original packaging. Once the pad is removed from the original packaging, storage in conditions outside of the recommended conditions may reduce the shelf life of the pad.

PRECAUTIONARY NOTES

Follow all MSDS label precautions and good industrial and hygiene practices when handling or using this product. Keep this and all industrial materials away from untrained personnel.

DISPOSAL

Dispose in accordance with all applicable regulations.

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